

WHAT IS CLAIMED IS:

1. A solid-state image pickup device comprising:
 - a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted; and
 - a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip, characterized in that
- 10 said solid-state image pickup element chip is formed on a substrate with a thermal expansion coefficient equal to that of said protection cap, and the substrate and said protection cap are sealed with a sealing resin.
- 15 2. The device according to claim 1, characterized in that said solid-state image pickup element chip is adhered onto the substrate with a flexible adhesive.
- 20 3. The device according to claim 1, characterized in that a contact preventive member is provided between each one of the plurality of solid-state image pickup elements and the sealing resin so the sealing resin will not come into contact with each one of the plurality of solid-state image pickup elements.
- 25 4. The device according to claim 1, characterized

in that the substrate is one of a glass substrate, ceramic substrate, metal substrate, and resin substrate, or a substrate formed by stacking some of the glass substrate, ceramic substrate, metal substrate, and resin substrate.

5. The device according to claim 1, characterized in that the sealing resin is a resin selected from the group consisting of epoxy-, acrylic, and phenol-based 10 resins.

6. The device according to claim 1, characterized in that said solid-state image pickup element chip is formed on the substrate through a light-shielding layer 15 that shields light.

7. A solid-state image pickup device comprising: a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are 20 mounted; and

a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip, characterized in that

25 said solid-state image pickup element chip is formed on a substrate made of the same material as that of said protection cap, and

the substrate and said protection cap are sealed with a sealing resin.

8. The device according to claim 7, characterized
5 in that said solid-state image pickup element chip is
adhered onto the substrate with a flexible adhesive.

9. The device according to claim 7, characterized
in that a contact preventive member is provided between
10 each one of the plurality of solid-state image pickup
elements and the sealing resin so the sealing resin
will not come into contact with each one of the
plurality of solid-state image pickup elements.

15 10. The device according to claim 7,
characterized in that the substrate is one of a glass
substrate, ceramic substrate, metal substrate, and
resin substrate, or a substrate formed by stacking some
of the glass substrate, ceramic substrate, metal
20 substrate, and resin substrate.

11. The device according to claim 7,
characterized in that the sealing resin is a resin
selected from the group consisting of epoxy-, acrylic,
25 and phenol-based resins.

12. The device according to claim 7,

characterized in that said solid-state image pickup element chip is

formed on the substrate through a light-shielding layer that shields light.